



#### **N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>A</sub> = 25°C
60V	2Ω @ V <sub>GS</sub> = 10V	540mA
000	3Ω @ V <sub>GS</sub> = 5V	430mA

## **Description and Applications**

This new generation MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

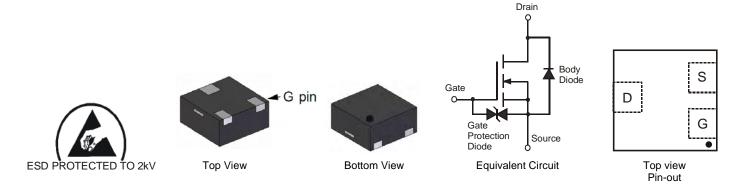
- DC-DC Converters
- Power management functions
- · Battery Operated Systems and Solid-State Relays
- Load switch

### **Features and Benefits**

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate to 2kV
- Lead Free/RoHS Compliant (Note 1)
- Green Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: X1-DFN1212-3
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.005 grams (approximate)



## **Ordering Information** (Note 3)

Part Number	Case	Packaging		
DMN62D0SFD-7	X1-DFN1212-3	3000/Tape & Reel		

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com

## **Marking Information**



K62 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Y = 2011) M = Month (ex: 9 = September)

Date Code Key

Year	20	07	20	008	20	09	20	10	20	11	20	12
Code	l	J	'	V	V	V	)	<	\	1	Z	7
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	60	V		
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current (Note EV)	Steady State	$T_A = 25$ °C $T_A = 70$ °C	I <sub>D</sub>	540 430	mA
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	t<10s	$T_A = 25$ °C $T_A = 70$ °C	I <sub>D</sub>	630 500	mA
Continuous Drain Current (Note 5) V	Steady State	$T_A = 25$ °C $T_A = 70$ °C	ΙD	430 340	mA
Continuous Drain Current (Note 5) V <sub>GS</sub> = 5V	T <sub>A</sub> = 25°C T <sub>A</sub> = 70°C	ID	510 410	mA	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	1.0	Α		
Maximum Body Diode Forward Current (Note 5)	I <sub>S</sub>	1.0	Α		

## Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 4)		$P_{D}$	0.43	W
Thermal Desistance, Junction to Ambient (Note 4)	Steady state	Б.	260	°C/W
Thermal Resistance, Junction to Ambient (Note 4)	t<10s	$R_{\theta JA}$	182	°C/W
Total Power Dissipation (Note 5)		$P_{D}$	0.89	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	Б	140	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	98	°C/W
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	112	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

## Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	ı	-	V	$V_{GS} = 0V, I_{D} = 10\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C	I <sub>DSS</sub>	-	-	100	nA	$V_{DS} = 60V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	-	-	10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)				-		_
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	1.6	2.5	٧	$V_{DS} = 10V, I_{D} = 1mA$
Static Drain-Source On-Resistance	D	-	1	2	Ω	$V_{GS} = 10V, I_D = 500mA$
Static Dialif-Source Off-Resistance	R <sub>DS (ON)</sub>	-	ı	3	52	$V_{GS} = 5V$ , $I_D = 50mA$
Forward Transfer Admittance	Y <sub>fs</sub>	-	130	-	mS	$V_{DS} = 3V, I_{D} = 30mA$
Diode Forward Voltage	$V_{SD}$	-	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 300mA$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C <sub>iss</sub>	-	30.2	-	pF	V 05)/ )/ 0)/
Output Capacitance	Coss	-	4.4	-	рF	$V_{DS} = 25V, V_{GS} = 0V,$ -f = 1.0MHz
Reverse Transfer Capacitance	Crss	-	2.8	-	pF	1 = 1.0lvii iz
Gate Resistance	Rg	-	131	-	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	-	0.39	-	nC	
Total Gate Charge (V <sub>GS</sub> = 10.0V)	Qg	-	0.87	-	nC	V 40V I 4A
Gate-Source Charge	Q <sub>gs</sub>	-	0.14	-	nC	$V_{DS} = 10V, I_{D} = 1A$
Gate-Drain Charge	$Q_{gd}$	-	0.09	-	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	-	3.95	-	ns	
Turn-On Rise Time	t <sub>r</sub>	-	3.81	-	ns	$V_{DS} = 30V, I_{D} = 200mA$
Turn-Off Delay Time	t <sub>D(off)</sub>	-	16.0	-	ns	$V_{GS} = 10V$ , $R_G = 25 \Omega$
Turn-Off Fall Time	t <sub>f</sub>	-	9.04	-	ns	

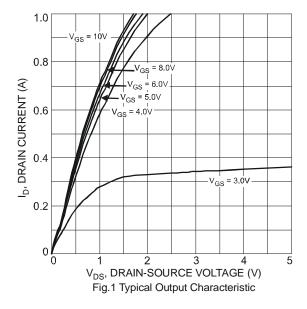
Notes: 4. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

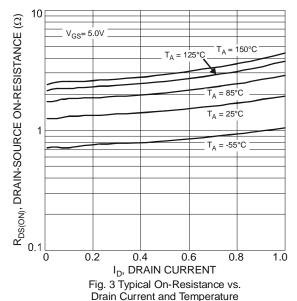
<sup>5.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate

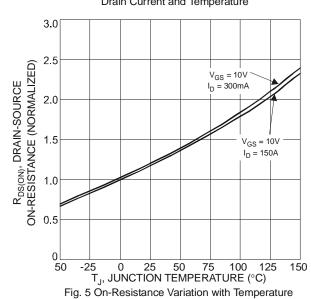
<sup>6 .</sup>Short duration pulse test used to minimize self-heating effect.

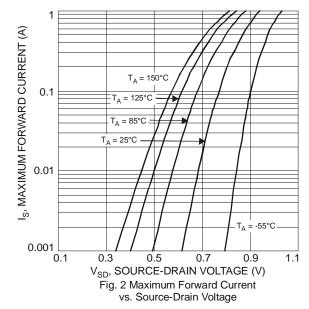
<sup>7.</sup> Guaranteed by design. Not subject to production testing.











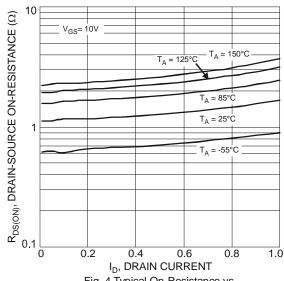


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

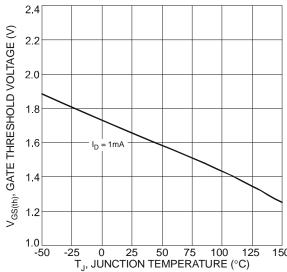
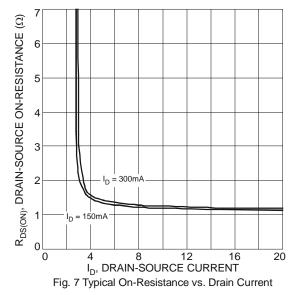
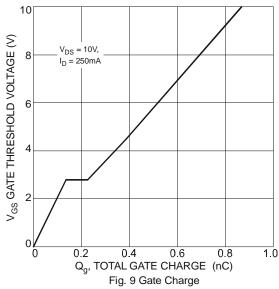


Fig. 6 Gate Threshold Variation vs. Ambient Temperature







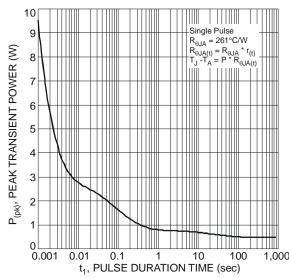
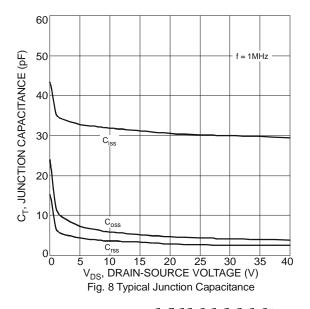
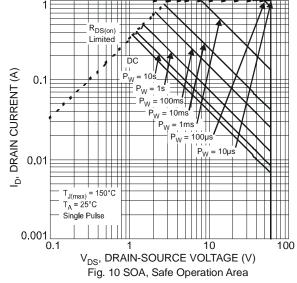
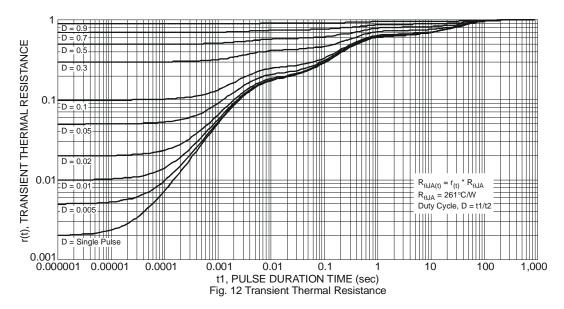


Fig. 11 Single Pulse Maximum Power Dissipation

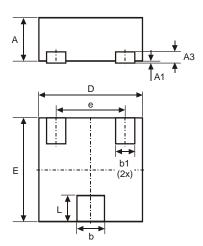






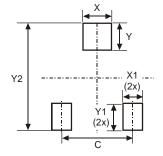


## **Package Outline Dimensions**



X1-DFN1212-3							
Dim	Min	Max	Тур				
Α	0.47	0.53	0.50				
<b>A</b> 1	0	0.05	0.02				
А3	•	•	0.13				
b	0.27	0.37	0.32				
b1	0.17	0.27	0.22				
D	1.15	1.25	1.20				
Е	1.15	1.25	1.20				
e	•	•	0.80				
Ĺ	0.25	0.35	0.30				
All Dimensions in mm							

## **Suggested Pad Layout**



Dimensions	Value (in mm)
С	0.80
X	0.42
X1	0.32
Y	0.50
Y1	0.50
Y2	1.50



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2011, Diodes Incorporated

www.diodes.com

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Diodes Incorporated:

DMN62D0SFD-7